

B1
Cont.
C1

a tape carrier defining a thickness;
a first adhesive layer disposed on the tape carrier, the first adhesive layer having a coefficient of thermal expansion and a thickness;

a transition medium having a first surface and a second surface, wherein the first surface of the transition medium engages the first adhesive layer, the transition medium having a coefficient of thermal expansion and a thickness;

a second adhesive layer disposed on the second surface of the transition medium, the second layer of adhesive having a coefficient of thermal expansion and a thickness;

a die disposed on the second adhesive layer comprising a thickness that is less than the thickness of the transition medium; and

a mold cap encapsulating the first adhesive layer, the transition medium, the second adhesive layer and the die, wherein the mold cap and tape carrier define a package thickness, wherein the thickness of the adhesive layer, transition medium and die is nearly equivalent to or the same as the half of the package thickness so as to reduce the stress on the die during thermal cycling, wherein the transition medium and the mold cap have approximately the same coefficient of thermal expansion so as to reduce the thermal stress on the die during thermal cycling.

B2
Sub
D1

49. (Amended) An integrated circuit package comprising:

an integrated circuit die having a front side, a back side, and a first thickness between the front and back sides, wherein bonding pads are formed on the front side;

a metallized polymer layer having a first side and a second side, wherein the bonding pads are electrically coupled to features of the metallized polymer layer; and

a transition medium, between the integrated circuit die and the metallized polymer layer, wherein the transition medium has a second thickness, greater than the first thickness.